

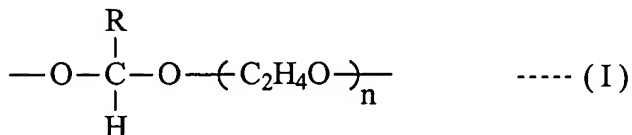
Complete set of claims

1(original). A chemically amplified positive-working photosensitive resin composition, comprising (A) an alkali soluble novolak resin, (B) an alkali soluble acrylic resin, (C) an acetal compound, and (D) an acid generator.

2(currently amended). The chemically amplified positive-working photosensitive resin composition according to claim 1, wherein the acrylic resin contains a structural unit derived from (methah)acrylic acid and a structural unit derived from alkyl methacrylate as well as a structural unit derived from styrene as needed.

3(original). The chemically amplified positive-working photosensitive resin composition according to claim 1, wherein the acrylic resin contains a structural unit derived from hydroxyalkyl methacrylate and a structural unit derived from alkyl methacrylate as well as a structural unit derived from styrene as needed.

4(currently amended). The chemically amplified positive-working photosensitive resin composition according to ~~any one of Claims 1 to 3~~ claim 1, wherein the acetal compound has a structural unit represented by the following general formula (I):



wherein R represents a saturated alkyl group having 1 to 20 carbon-atoms; and n is an integer of 1 to 10.

5(currently amended). The chemically amplified positive-working photosensitive resin composition according to ~~any one of Claims 1 to 4~~ claim 1, wherein the weight ratio of the components (A):(B):(C):(D) is 100 : (2 to 200) : (1 to 50) : (0.05 to 10).

6(currently amended). The chemically amplified positive-working photosensitive resin composition according to ~~any one of Claims 1 to 5~~ claim 1, wherein the chemically amplified positive-working photosensitive resin is used for producing a film of 5 μm or more in thickness.

7(currently amended). ~~The chemically amplified positive-working photosensitive resin composition according to any one of Claims 1 to 6, wherein the chemically amplified positive-working photosensitive resin composition is used in~~ A process comprising a cyan or non-cyan electrolytic gold-plating step in the gold bump-forming process of the semiconductor packaging technology, and further comprising imaging the chemically amplified positive-working photosensitive resin composition of claim 1.

8(currently amended). ~~The chemically amplified positive-working photosensitive resin composition according to any one of Claims 1 to 6, wherein the chemically amplified positive-working photosensitive resin composition is used in~~ A process comprising a copper-, nickel-, or solder-plating step, and further comprising

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imaging of the chemically amplified positive-working photosensitive resin composition of claim 1.

9(currently amended). ~~The chemically amplified positive-working photosensitive resin composition according to any one of Claims 1 to 6,~~ The process of claim 7 wherein the chemically amplified positive-working photosensitive resin composition is used in continuous plating steps ~~of claims 7 and 8.~~

10(new). The process of claim 8, wherein the chemically amplified positive-working photosensitive resin composition is used in continuous plating steps.